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Docket No. 220254US2PCT

FEB 26 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

3742
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IN RE APPLICATION OF: Yasuji HIRAMATSU, et al.

SERIAL NO: 10/069,510

GAU: 3742

FILED: June 20, 2002

EXAMINER: FUQUA, SHAWNTINA T

FOR: HOT PLATE FOR SEMICONDUCTOR PRODUCING/EXAMINING DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

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REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the application(s) is attached along with PTO 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 220254US2PCT	SERIAL NO. 10/069,510
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Yasuji HIRAMATSU, et al.			
		FILING DATE June 20, 2002		GROUP 3742	
U.S. PATENT DOCUMENTS					
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS SUB CLASS
	AA	6,507,006	01/14/03	HIRAMATSU et al.	
	AB	6,465,763	10/15/02	ITO et al.	
	AC	6,677,557	01/13/04	ITO et al.	
	AD	6,475,606	11/05/02	NIWA	
	AE				
	AF				
	AG				
	AH				
	AI				
	AJ				
	AK				
	AL				
	AM				
	AN				
FOREIGN PATENT DOCUMENTS					
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO
	AO				
	AP				
	AQ				
	AR				
	AS				
	AT				
	AU				
	AV				
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)					
	AW	Pub. No. US 2003/015521 A1 Appln. No. 10/217,029	Pub. Date: Jan. 23, 2003 Filed: Aug.13, 2002	Inventor: Yasutaka ITO	
	AX	Pub. No. US 2002/0043527 A1 Appln. No. 09/915,418	Pub. Date: Apr. 18, 2002 Filed: Jul. 27, 2001	Inventor: Yasutaka ITO	
	AY				
	AZ				<input type="checkbox"/> Additional References sheet(s) attached
Examiner				Date Considered	

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent Number</u>	<u>Filing or Issue Date</u>	<u>Inventor/Applicant</u>
PER CLIENT	09/471,759	12/23/99	SAITO et al.
PER CLIENT	09/462,067	01/05/01	FURUKAWA et al.
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*Present Application; listed for information

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